

Features

- 20V/55A,
 $R_{DS(ON)} = 4.9m\Omega(Typ.)@V_{GS}=4.5V$
 $R_{DS(ON)} = 5.1m\Omega(Typ.)@V_{GS}=3.8V$
 $R_{DS(ON)} = 5.4m\Omega(Typ.)@V_{GS}=3.1V$
 $R_{DS(ON)} = 6m\Omega(Typ.)@V_{GS}=2.5V$
 $R_{DS(ON)} = 9.5m\Omega(Typ.)@V_{GS}=1.8V$
- Low $R_{DS(ON)}$
- Super High Dense Cell Design

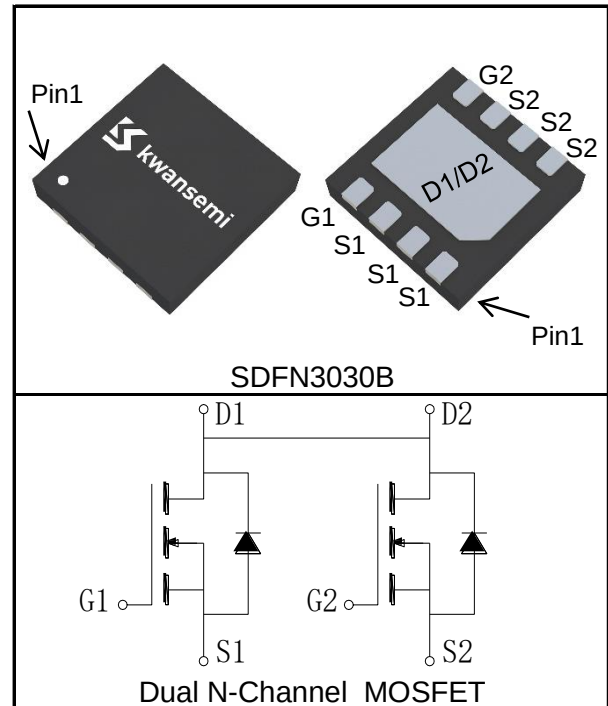
Applications

- Power Management
- Battery Protection



Halogen-Free

Pin Description



Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
Common Ratings (T _C =25°C Unless Otherwise Noted)				
V _{DSS}	Drain-Source Voltage		20	V
V _{GSS}	Gate-Source Voltage		±12	
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to 150	°C
I _S	Diode Continuous Forward Current	T _C =25°C	55	A
Mounted on Large Heat Sink				
I _{DP} ^①	300μs Pulse Drain Current Tested	T _C =25°C	220	A
I _D ^②	Continuous Drain Current@T _C (V _{GS} =4.5V)	T _C =25°C	55	A
		T _C =100°C	35	
	Continuous Drain Current@T _A (V _{GS} =4.5V) ^③	T _A =25°C	19	
		T _A =70°C	15	
P _D	Maximum Power Dissipation@T _C	T _C =25°C	30	W
		T _C =100°C	12	
	Maximum Power Dissipation@T _A ^③	T _A =25°C	3.6	
		T _A =70°C	2.3	

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	4.1	$^{\circ}\text{C/W}$
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	35	$^{\circ}\text{C/W}$
Drain-Source Avalanche Ratings			
$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	36	mJ

Electrical Characteristics ($T_C=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	KS2416UA3			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V			1	μA
		T _J =125°C			30	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	0.4	0.7	1	V
I _{GSS}	Gate Leakage Current	V _{GS} =±12V, V _{DS} =0V			±100	nA
R _{DS(ON)} ⑤	Drain-Source On-state Resistance	V _{GS} =4.5V, I _{DS} =3A	3.5	4.9	5.9	mΩ
		V _{GS} =3.8V, I _{DS} =3A	4	5.1	6.2	mΩ
		V _{GS} =3.1V, I _{DS} =3A	4	5.4	6.5	mΩ
		V _{GS} =2.5V, I _{DS} =3A	4.5	6	7.5	mΩ
		V _{GS} =1.8V, I _{DS} =3A	6	9.5	13	mΩ
Diode Characteristics						
V _{SD} ⑤	Diode Forward Voltage	I _{SD} =3A, V _{GS} =0V		0.74	1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} =3A, dI _{SD} /dt=100A/μs		17		ns
Q _{rr}	Reverse Recovery Charge			33		nC
Dynamic Characteristics ⑥						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		1.6		Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, Frequency=1.0MHz		1415		pF
C _{oss}	Output Capacitance			230		
C _{rss}	Reverse Transfer Capacitance			150		
t _{d(ON)}	Turn-on Delay Time	V _{DD} =10V, I _{DS} =3A, V _{GS} =4,5V, R _G =6Ω		8		ns
t _r	Turn-on Rise Time			12		
t _{d(OFF)}	Turn-off Delay Time			23		
t _f	Turn-off Fall Time			14		
Gate Charge Characteristics ⑥						
Q _g	Total Gate Charge	V _{DS} =10V, V _{GS} =4,5V, I _{DS} =3A		19		nC
Q _{gs}	Gate-Source Charge			6.2		
Q _{gd}	Gate-Drain Charge			7.9		

Notes:

- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 40A.
- ③When mounted on 1 inch square copper board, $t \leq 10\text{sec}$.
- ④Limited by T_{Jmax} , $I_{AS} = 12\text{A}$, $L = 0.5\text{mH}$, $V_{DD} = 15\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.
- ⑤Pulse test; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- ⑥Guaranteed by design, not subject to production testing.

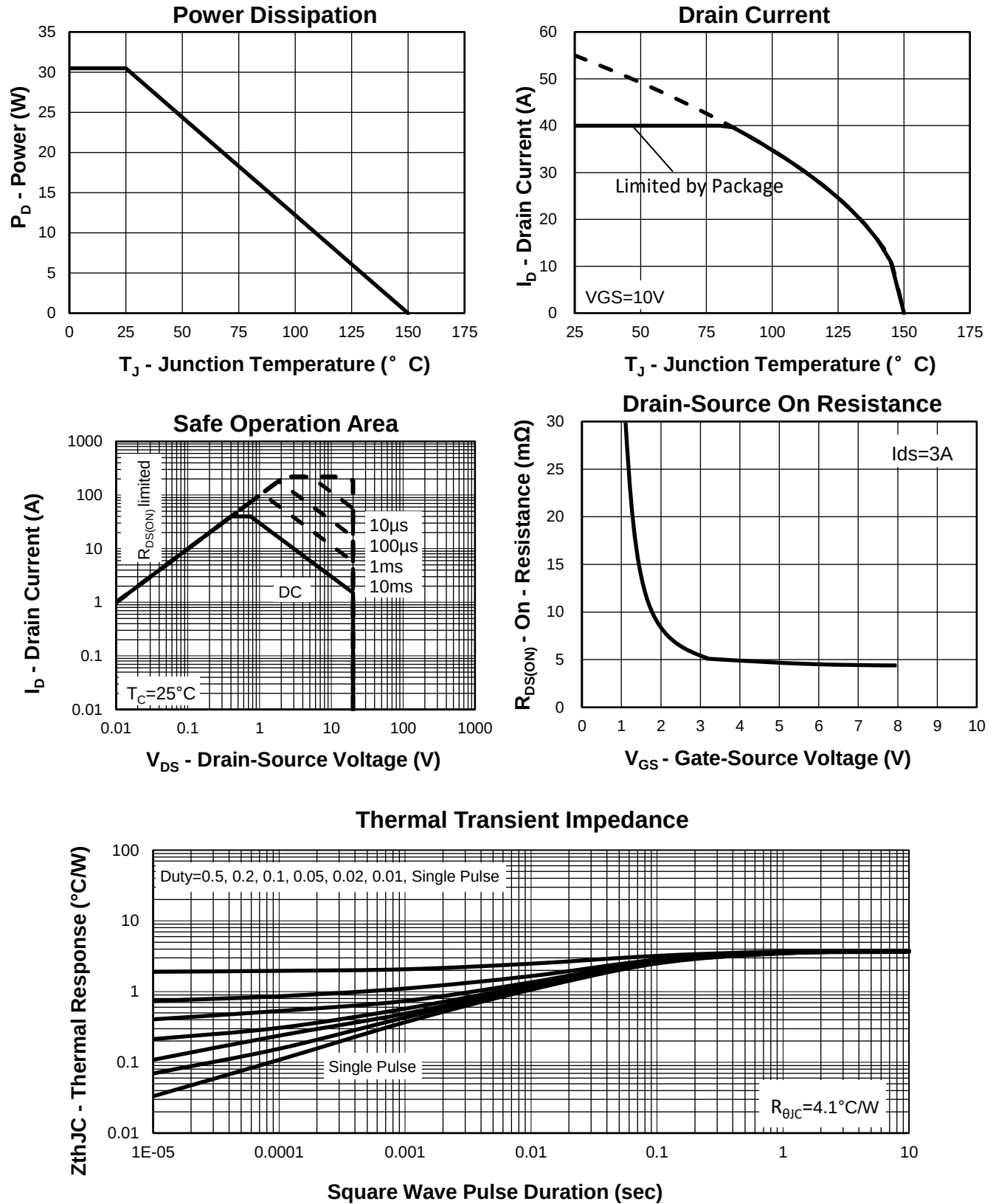
Ordering and Marking Information

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS2416UA3	SDFN3030B	Tape&Reel	5000	13"	12mm

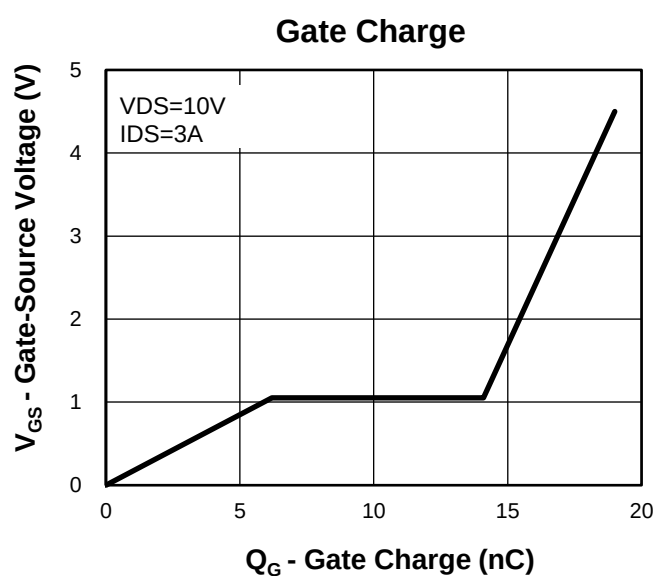
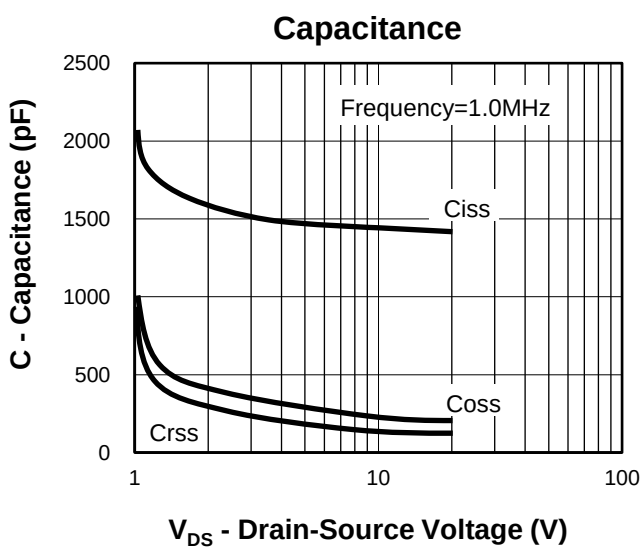
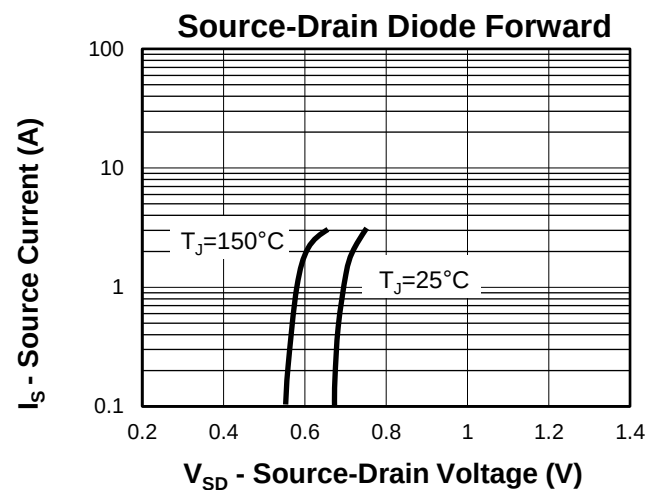
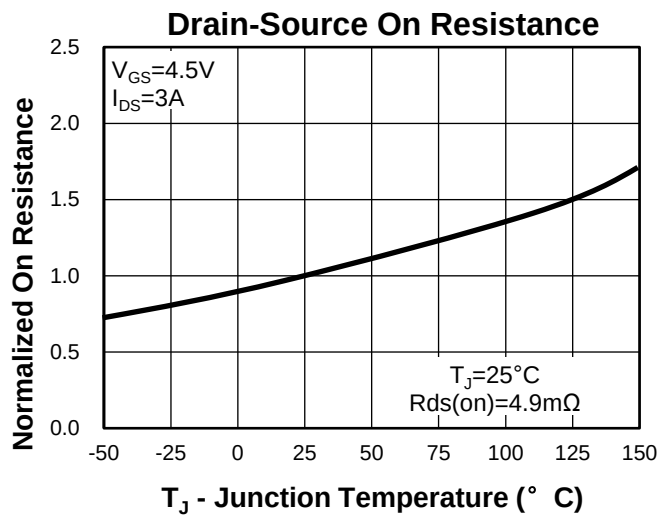
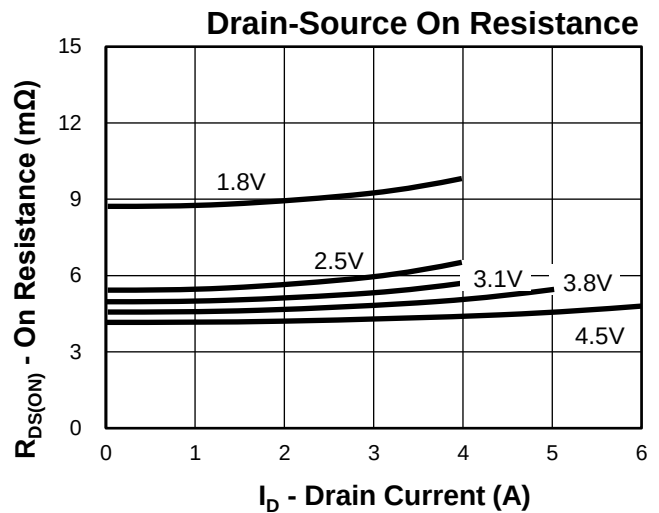
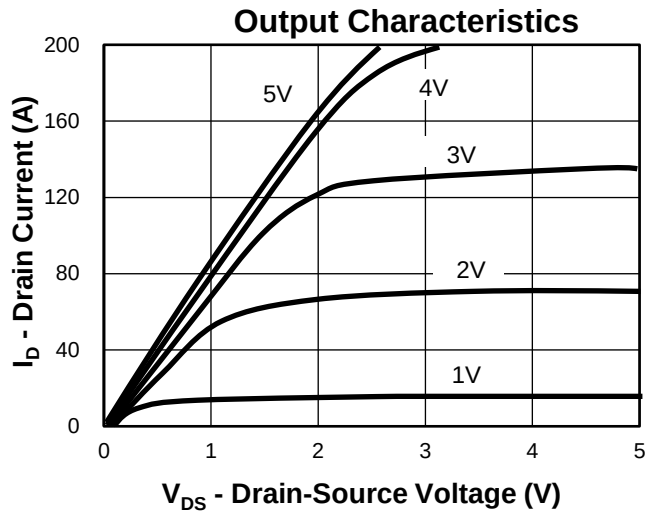


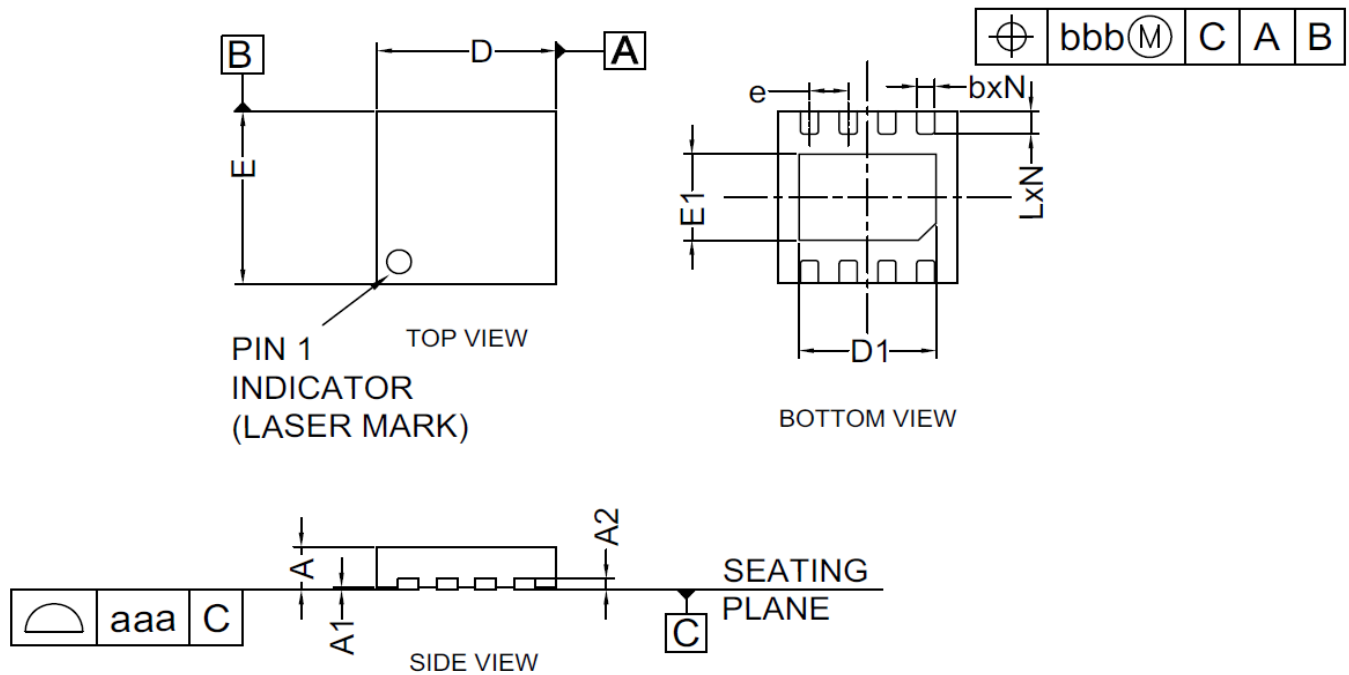
1st Line: Kwansemi Code(KS)
2nd Line: Part Number(2416)
3rd Line: Lot Number(YWWXXX)

Typical Characteristics



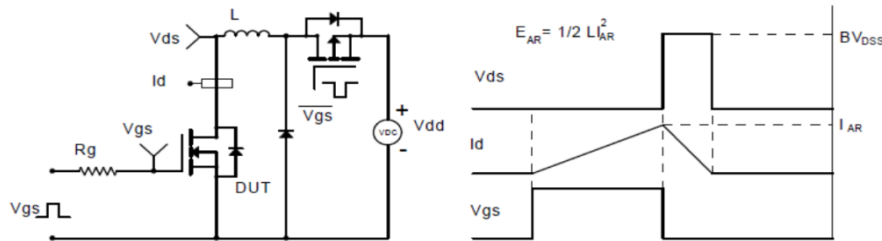
Typical Characteristics



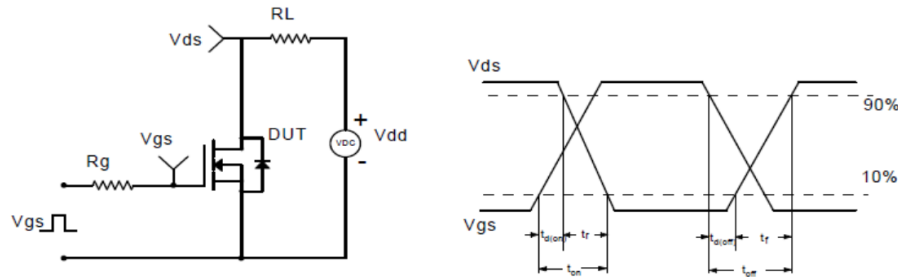
Package Information
SDFN3030B


SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
A2	0.203 REF			0.008 REF		
b	0.25	0.30	0.35	0.010	0.012	0.014
D	2.90	3.00	3.10	0.114	0.118	0.122
D1	2.20	2.30	2.40	0.087	0.091	0.094
E	2.90	3.00	3.10	0.114	0.118	0.122
E1	1.40	1.50	1.60	0.055	0.059	0.063
e	0.65 BSC			0.026 BSC		
L	0.35	0.40	0.45	0.014	0.016	0.018
K	0.20	-	-	0.008	-	-
aaa	0.08 REF			0.003 REF		
bbb	0.10 REF			0.004 REF		

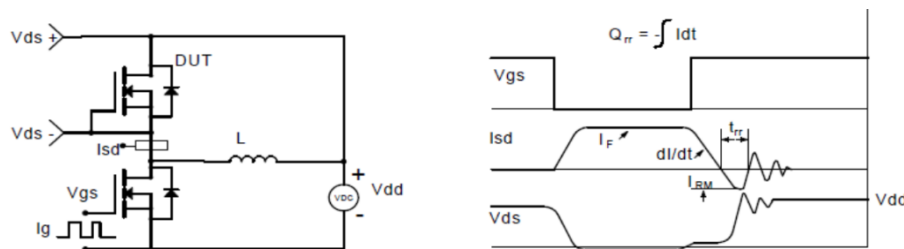
Avalanche Test Circuit and Waveforms



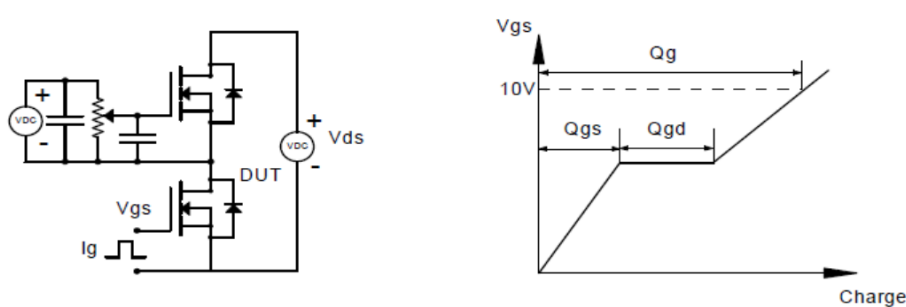
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

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